

SPECIFICATION FOR LCD MODULE

MODULE NO: AFK800480A0-7.0N12NTH REVISION NO: V01

Customer's Approval:		
	SIGNATURE	DATE
PREPARED BY (RD ENGINEER)		
CHECKED BY		
APPROVED BY		

Records of Revision

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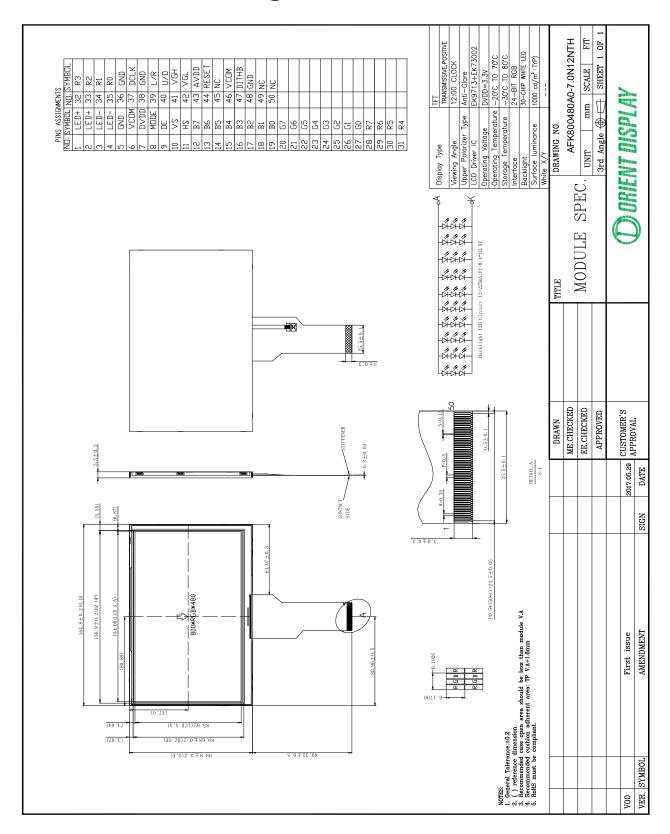
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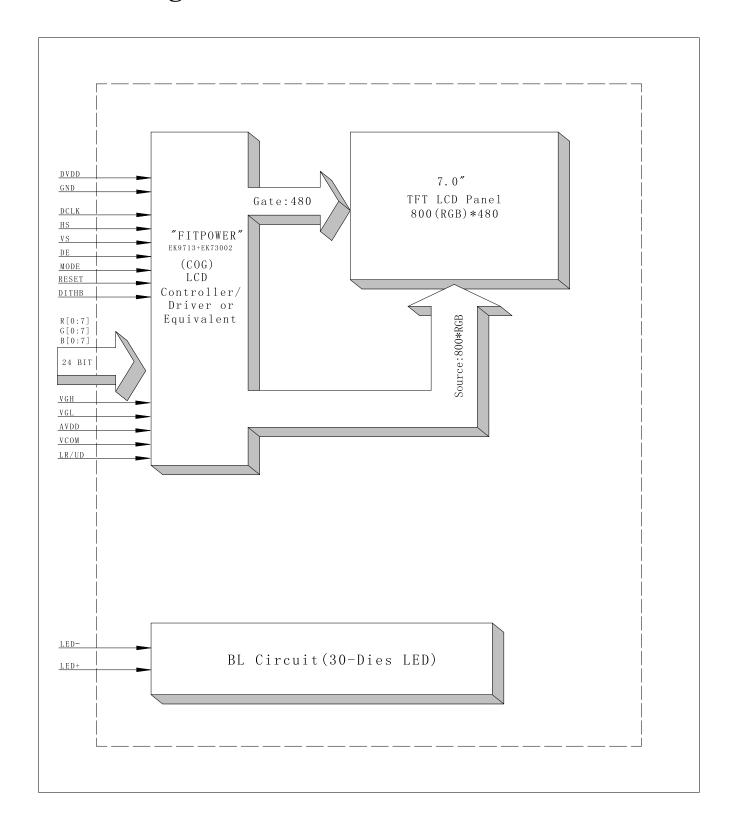
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	164.80*99.80*5.5	MM
ACTIVE SIZE (W*H)	154.08*85.92	MM
PIXEL PITCH (W*H)	0.1926*0.1790	MM
NUMBER OF DOTS	800*480	
DIVER IC	EK9713+EK73002	
INTERFACE TYPE	24-BIT RGB	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	12	O'CLOCK
GRAY SCALE INVERSION DIRECTION	6	O'CLOCK
COLORS	16.7M	
BACKLIGHT TYPE	30-LED WHITE	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	LED+	Anode of LED backlight
2	LED+	Anode of LED backlight
3	LED-	Cathode of LED backlight
4	LED-	Cathode of LED backlight
5	GND	Power ground
6	VCOM	Common voltage
7	DVDD	Power for digital circuit
8	MODE	DE/SYNC mode select
9	DE	Data input enable
10	VS	Vertical sync input
11	HS	Horizontal sync input
12	В7	Blue data(MSB)
13	В6	Blue data
14	B5	Blue data
15	B4	Blue data
16	В3	Blue data
17	B2	Blue data
18	B1	Blue data
19	В0	Blue data(LSB)
20	G7	Blue data(LSB)
21	G6	Green data
22	G5	Green data
23	G4	Green data
24	G3	Green data
25	G2	Green data
26	G1	Green data
27	G0	Green data(LSB)
28	R7	Red data(MSB)
29	R6	Red data
30	R5	Red data
31	R4	Red data
32	R3	Red data
33	R2	Red data
34	R1	Red data
35	R0	Red data(LSB)
36	GND	Power Ground
37	DCLK	Sample clock
38	GND	Power Ground
39	L/R	Left / right selection
40	U/D	Up/down selection
41	VGH	Gate ON Voltage

42	VGL	Gate OFF Voltage
43	AVDD	Power for Analog Circuit
44	RESE	Global reset pin.
	T	
45	NC	No connection
46	VCOM	Common Voltage
47	DITHB	Dithering function
48	GND	Power Ground
49	NC	No connection
50	NC	No connection

Note1: If LVDS input data is 6 bits ,SELB must be set to High;

If LVDS input data is 8 bits ,SELB must be set to Low.

Note2: When CABC EN="00", CABC OFF.

When CABC_EN="01", user interface image.

When CABC EN="10", still picture.

When CABC_EN="11", moving image.

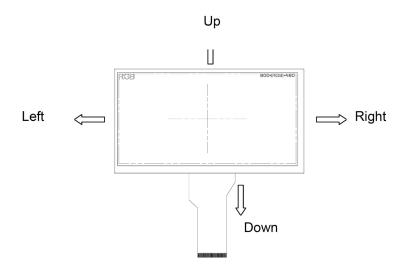
When CABC off, don't connect DIMO, else connect it to backlight.

Note3: When L/R="0", set right to left scan direction.

When L/R="1", set left to right scan direction.

When U/D="0", set top to bottom scan direction.

When U/D="1", set bottom to top scan direction.



5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for logic	DVDD	-0.3	5	V
Supply voltage for analog	AVDD	0.5	13.5	V
Power supply	VGH	0.3	40	V
Power supply	VGL	-20	0.3	V
Power supply	VGH- VGL	-	40	V
Supply current (One LED)	I_{LED}		30	mA
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T_{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage for Logic	DVDD	3.0	3.3	3.6	V	
Supply Voltage for Analog	AVDD	10.2	10.4	10.6	V	
Power supply	VGH	15.3	16	16.7		
Power supply	VGL	-7.7	-7	-6.3		
Power supply	VCOM	2.6	3.6	4.6		
Input Voltage	$V_{\rm IL}$	GND	-	0.3DVD D	V	
	$ m V_{IH}$	0.7 DVDD	-	DVDD		
Input leakage Current	I_{LKG}	-		-	μА	

6.2 Backlight Driving Conditions

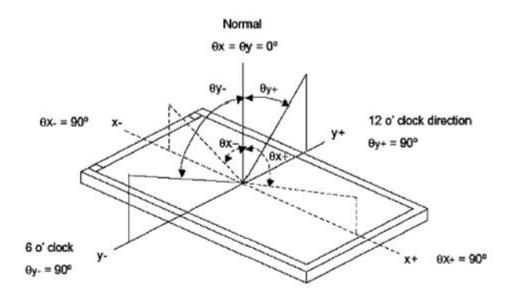
Itom	Crush al		Value	TT\$4	Remar	
Item	Symbol	Min.	Typ.	Max.	Unit	k
Voltage for LED Backlight	VF	8.4	9.3	10.5	V	I _L =225mA
Current for LED Backlight	IL		225		mA	
Power Consumption	P		2.092		W	
LED Life Time		30,000	50000		Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25 $^{\circ}\text{C}$

7. Optical Characteristics

LUNDA	Л	CVMDOI	CONDITIONS	SPEC	IFICAT	ΓIONS	TINITE	NOTE
ITEN	VI.	SYMBOL	CONDITIONS	MIN		MAX	UNIT	NOTE
Lumina	nce	L	I _L =225mA	800	1000	1200	Cd/m ²	
Contrast l	Ratio	CR	θ=0°	400	500			
Dagnanga	Timo	Ton	25℃		10	20	122 G	
Response	Time	Toff	23 0		15	30	ms	
Red		XR						
Kcu	YR							
	Green	XG						
CIE Color	Green	YG	Viewing normal					
Coordinate	Blue	Хв	angle					
	Blue	Yв						
	White	Xw						
	Wille	Yw						
	Hor.	$ heta_{\scriptscriptstyle X+}$		60	70			
Viewing	1101.	$ heta_{\scriptscriptstyle X-}$	CR≥10	60	70		Degree	
Angle	Ver.	$ heta_{\scriptscriptstyle Y+}$	CK>10	40	50		Degree	
	V C1.	$ heta_{\scriptscriptstyle Y-}$		60	70			
Uniformity	Un			70	75		%	

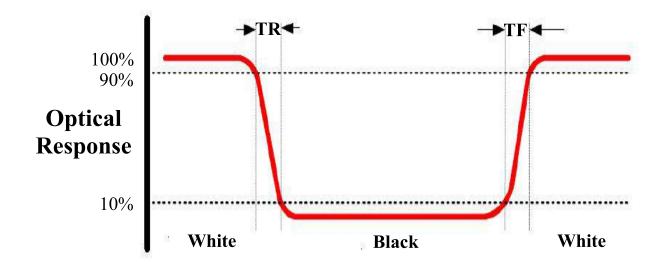
Note 1: Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance of white state}{Luminance of black state}$$

Note 3: Definition of Response Time(Tr,Tf)

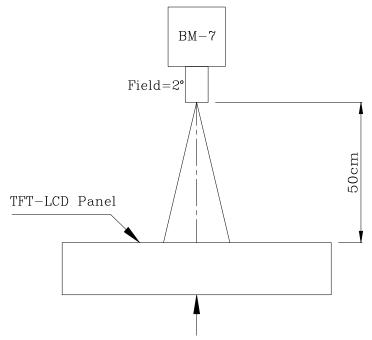


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Note 4: Definition of Luminance

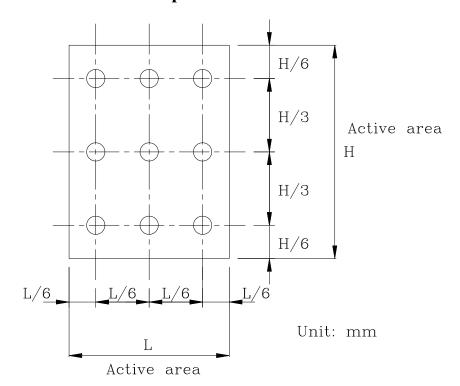
①The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)



The center of the screen

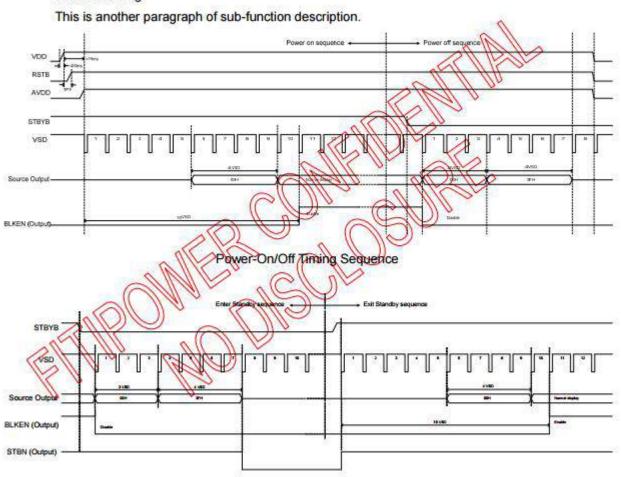
②The Brightness Test Point Setup



8. Timing Characteristics

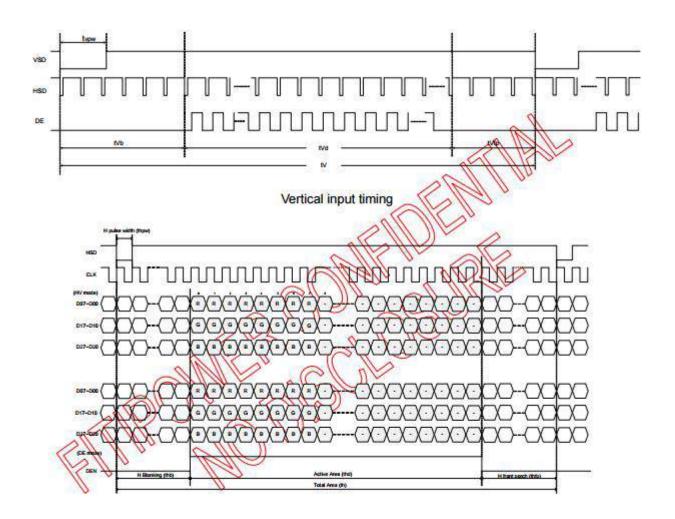
8.1 POWER SEQUENCE

In order to prevent IC from power on reset fail, the rising time (TPOR) of the digital power supply VDD should be maintained within the given specifications. Refer to "AC Characteristics" for more detail on timing.



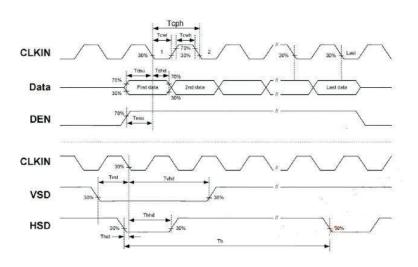
Enter and Exit Standby Mode Sequence

8.2 Data input format



Horizontal input timing

8.3 RGB MODE TIMING DIAGRAM



8.4 RGB TIMING TABLE

Item	Symbol	Values			Unit	Remark
item	Symbol	Min.	Тур.	Max.	Oille	Remark
Horizontal Display Area	thd		800		DCLK	
DCLK Frequency	fclk	26.3	33.3	46.8	MHz	
One Horizontal Line	th	862	1056	1200	DCLK	
HS pulse width	thpw	1		40	DCLK	
HS Blanking	thb	46	46	46	DCLK	
HS Front Porch	thfp	16	210	354	DCLK	

Item	0		Values			
	Symbol	Min.	Тур.	Max.	- Unit	Remark
Vertical Display Area	tvd		480		TH	
VS period time	tv	510	525	650	TH	
VS pulse width	tvpw	1		20	TH	
VS Blanking	tvb	23	23	23	TH	
VS Front Porch	t√fp	7	22	147	TH	

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

	2.1 Standard Specification for Kenability of LCD Module					
No.	Item	Description	Remarks			
01	High temperature operation	The sample should be allowed to stand at 70°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.	Note 1 IEC60068-2-2, GB2423.2-89			
02	Low temperature operation	The sample should be allowed to stand at -20°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.	Note2 IEC60068-2-1 GB2423.1-89			
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.	IEC60068-2-2 GB2423.2-89			
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.	IEC60068-2-1 GB/T2423.1-89			
05	Moisture storage	The sample should be allowed to stand at $60^{\circ}\text{C},90\%\text{RH}$ MAX for 240hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.	IEC60068-2-1 GB/T2423.3-2006			
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: $-20^{\circ}\text{C} \text{ for } 30 \text{ minutes} \rightarrow \text{normal temperature for 5}$ $\text{minutes} \rightarrow +60^{\circ}\text{C} \text{ for } 30 \text{ minutes} \rightarrow \text{normal}$ $\text{temperature for 5 minutes, as one cycle.}$	Start with cold temperature, end with high temperature IEC60068-2-14, GB2423.22-87			
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.	IEC61000-2-6 GB/T2423.5-1995			
08	Packing drop test	According to ASTM-D-5327.	IEC60068-2-32 GB/T2423.8-1995			
09	Electrical Static	Air: ± 8 KV 150pF/330 Ω 5 times	IEC61000-4-2			
09	Discharge	Contact: ±4KV 150pF/330Ω 5 time	GB/T17626.2-1998			

Note:1.Ts is the temperature of panel's surface.

^{2.} Ta is the ambient temperature of sample.

^{3.} Sample size for each test item is 3~5pcs.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

deterioration within 50,000 hours	ce, etc. shall be free from remarkable s under ordinary operating and storage 5° C), normal humidity (50±10% RH), and nt.
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10. General Precautions

10.1. Safety

• Liquid crystal is poisonous. Do not put it in your mouth. If liquid crystal touches your skin or clothes, wash it off immediately by using soap and water.

10.2. Handling

- The LCD panel is plate glass. Do not subject the panel to mechanical shock or to excessive force on its surface.
- The polarizer attached to the display is easily damaged. Please handle it carefully to avoid scratch or other damages.
- To avoid contamination on the display surface, do not touch the module surface with bare hands.
- Keep a space so that the LCD panels do not touch other components.
- Put cover board such as acrylic board on the surface of LCD panel to protect panel from damages.
- Transparent electrodes may be disconnected if you use the LCD panel under environmental conditions where the condensation of dew occurs.
- Do not leave module in direct sunlight to avoid malfunction of the ICs.

10.3. Static Electricity

- Be sure to ground module before turning on power or operating module.
- Do not apply voltage which exceeds the absolute maximum rating value.

10.4. Storage

- Store the module in a dark room where must keep at $25\pm10^{\circ}$ C and 65%RH or less.
- Do not store the module in surroundings containing organic solvent or corrosive gas.
- Store the module in an anti-electrostatic container or bag.

10.5. Cleaning

- Do not wipe the polarizer with dry cloth. It might cause scratch.
- Only use a soft sloth with IPA to wipe the polarizer, other chemicals might permanent damage to the polarizer.

11. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Tecenstar.

11.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

11.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65Minor defect: AQL = 2.5Total defects: AQL = 2.5

11.3 Non-conforming Analysis & Deal With Manners

11.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

11.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

11.4 Agreement items

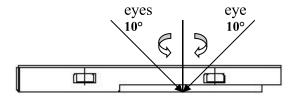
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

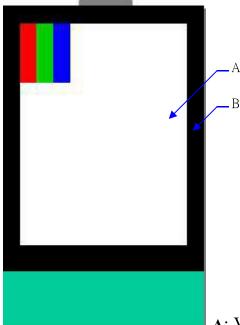
11.5 Standard of The Product Appearance Test

11.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5 °C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

11.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

11.6 Inspection Specification

NO.	Item		Cri	terion		AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 				0.65
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black orFive spots.2.2 Densely spaced: No	-			2.5
	LCD and Touch Panel black spots, white	3.1 Round type: As foll $\Phi = (X+Y)/2$ * Densely spaced: No		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$	Acceptable Q'ty Accept no dense 2 2 1 0 o spots within 3mm.	2.5
03	spots, write spots, contaminati on (non – display)	3.2 Line type: (As follo	Length(mm) L≤3.0 L≤2.5	mg) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty Accept no dense 2 Rejection vo lines within 3mm.	2.5

ches	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction Follow NO.3 -2 Line Type. Symbols: x: Chip length y: Chip width k: Seal width t: Glass thickness L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and craw	Size $\Phi(mm)$ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ $Total Q'ty$ z: Chip thickness as a: LCD side length ack between panels:	Acceptable Q'ty Accept no dense 3 2 0 3	2.5
oles	to find, must check in specify direction Follow NO.3 -2 Line Type. Symbols: x: Chip length y: Chip width k: Seal width t: Glass thickness L: Electrode pad length 6.1 General glass chip:	$0.50 < \Phi \le 1.00$ $1.00 < \Phi$ $Total Q'ty$ $z: Chip thickness$ as a: LCD side length	3 2 0	2.5
	Follow NO.3 -2 Line Type. Symbols: x: Chip length y: Chip width k: Seal width t: Glass thicknes L: Electrode pad length 6.1 General glass chip:	$0.50 < \Phi \le 1.00$ $1.00 < \Phi$ $Total Q'ty$ $z: Chip thickness$ as a: LCD side length	0	
ches	Symbols: x: Chip length y: Chip width k: Seal width t: Glass thicknes L: Electrode pad length 6.1 General glass chip:	1.00< Φ Total Q'ty z: Chip thickness as a: LCD side length		
ches	Symbols: x: Chip length y: Chip width k: Seal width t: Glass thicknes L: Electrode pad length 6.1 General glass chip:	z: Chip thickness as a: LCD side length	3	
ches	Symbols: x: Chip length y: Chip width k: Seal width t: Glass thicknes L: Electrode pad length 6.1 General glass chip:	ss a: LCD side length		
	x: Chip lengthk: Seal widtht: Glass thicknessL: Electrode pad length6.1 General glass chip:	ss a: LCD side length		
ped ss	$Z \le 1/2t$ Not over v area $1/2t < z \le 2t$ Not excee	viewing a $x \le 1/8a$ ed 1/3k $x \le 1/8a$ s the total length of each h x : Chip length viewing a $x \le 1/8a$	chip	2.5
		z: Chip thickness $z \le 1/2t$	z: Chip thickness y: Chip width x: Chip leng $Z \le 1/2t$ Not over viewing $x \le 1/8a$ area $1/2t < z \le 2t$ Not exceed $1/3k$ $x \le 1/8a$ $Or initial Unit: mm$	z: Chip thickness y: Chip width x: Chip length $Z \le 1/2t$ Not over viewing area $1/2t < z \le 2t$ Not exceed $1/3k$ $x \le 1/8a$

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$ $7.2.2$	
07	Glass crack	Non-conductive portion:	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$	
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack y: width x: length y = 1/3L X ≤ a	

NO.	Item	Criterion			
14	Touch Panel Chipped glass	k: Seal width t: 'L: Electrode pad len 14.1 General glass con 14.1.1 Chip on panel z: Chip thickness Z≦t O Unit: mm	y: Chip width ≤ 1/2 k and not over viewing area	x: Chip length x ≤ 1/8a	
		z: Chip thickness z≤t	y: Chip width ≤ 1/2 k and not over viewing area	x: Chip length $x \le 1/8a$	
		○ Unit: mm○ If there are 2 or n	nore chips, x is the total	length of each chip	

NO.	Item	Criterion		
15	Touch Panel(Fish eye dent and bubble on film)	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.		
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5	
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5	
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65	

12.Packing Method

----TBD